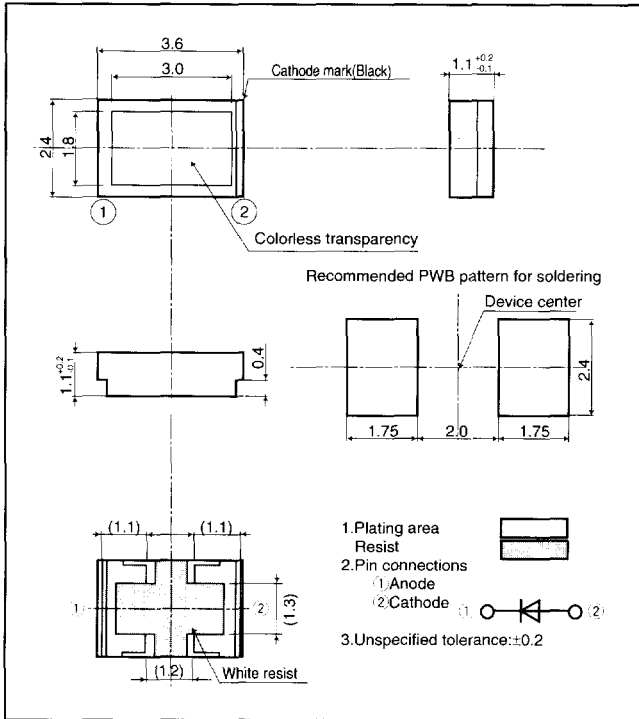


LT1□92A series

3624 Size, 1.1 mm Thickness, High-luminosity, MID* Type Leadless Chip LED Devices

Outline Dimensions

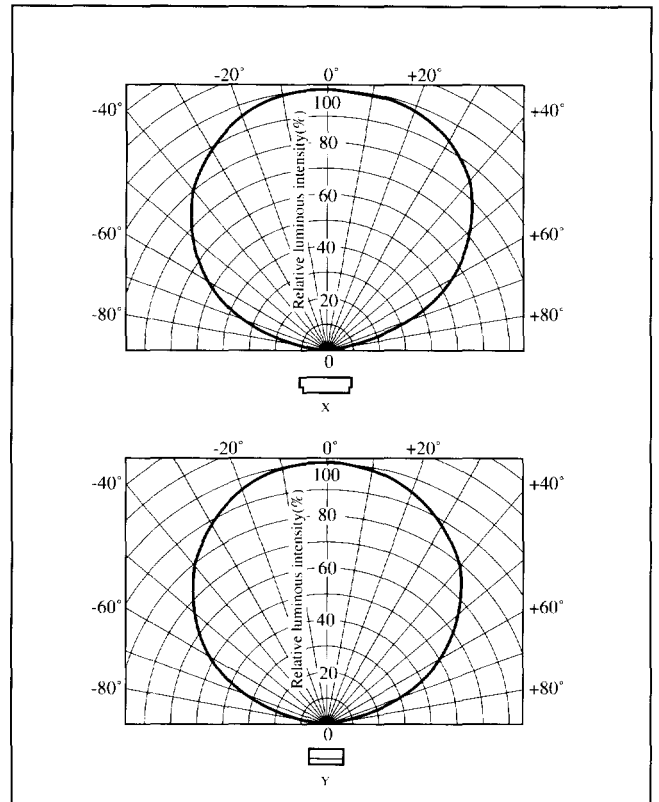
(Unit : mm)



*MID: Molded Interconnection Device

Radiation Diagram

(T_a=25°C)



Absolute Maximum Ratings

(T_a=25°C)

Model No.	Radiation color	Radiation material	Power dissipation P (mW)	Forward current I _F (mA)	Peak forward current I _{FM} *1 (mA)	Derating factor (mA/°C)		Reverse voltage V _R (V)	Operating temperature T _{opr} (°C)	Storage temperature T _{stg} (°C)	Soldering temperature T _{sol} *2 (°C)
						DC	Pulse				
LT1D92A	Red	GaAsP on GaP	84	30	50	0.40	0.67	5	-25 to +85	-25 to +100	260
LT1S92A	Sunset orange	GaAsP on GaP	84	30	50	0.40	0.67	5	-25 to +85	-25 to +100	260
LT1H92A	Yellow	GaAsP on GaP	84	30	50	0.40	0.67	5	-25 to +85	-25 to +100	260
LT1E92A	Yellow-green	GaP	84	30	50	0.40	0.67	5	-25 to +85	-25 to +100	260
LT1K92A	Green	GaP	84	30	50	0.40	0.67	5	-25 to +85	-25 to +100	260

*1 Duty ratio=1/10, Pulse width=0.1ms

*2 For 3s or less at the temperature of hand soldering. Temperature of reflow soldering is shown on the page 7.

Electro-optical Characteristics

(T_a=25°C)

Lens type	Model No.	Forward voltage V _F (V)		Peak emission wavelength		Luminous intensity		Spectrum radiation bandwidth		Reverse current		Terminal capacitance		Page for characteristics diagrams
		TYP	MAX	λ _p (nm)	I _F (mA)	I _v (mcd)	I _F (mA)	Δλ(nm)	I _F (mA)	I _r (μA)	V _R (V)	C(pF)	(MHz)	
Colorless transparency	LT1D92A	2.0	2.8	635	20	15.0	20	35	20	10	4	20	1	138
	LT1S92A	2.0	2.8	610	20	17.0	20	35	20	10	4	15	1	139
	LT1H92A	2.0	2.8	585	20	16.0	20	30	20	10	4	35	1	139
	LT1E92A	2.1	2.8	565	20	32.0	20	30	20	10	4	35	1	140
	LT1K92A	2.1	2.8	555	20	7.6	20	25	20	10	4	40	1	140